

**EAST Search History****EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	369	(264/614).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/09/01 18:57
L2	1181	(438/510).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/09/01 18:57
L3	19	straboni-alain.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/01 18:57
L4	70	silicon with germanium with powder and melt\$3 and compres\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/01 18:57
L5	6707	silicon with powder and melt\$3 and compres\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/01 18:58
L6	185	silicon with powder same compress\$3 same thermal	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/01 18:58
L7	43	silicon with powder same (compress\$3 or compact\$3) same melt\$3 and dop\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/01 19:06
L8	177	silicon with powder same (compress\$3 or compact\$3) same (melt\$3 or sinter\$3) and dop\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/09/01 19:07
S1	3	santana and polysilicon and silicon with powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/12 21:40
S2	85	polysilicon with wafer and silicon with powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/12 21:49
S3	30	polysilicon with wafer and silicon with powder and dop\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/12 21:49
S4	54494	silicon with powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/15 20:55

S5	198	silicon with powder same compress\$3 same melt\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/15 20:56
S6	339	silicon with powder same compress\$3 same (thermal or melt\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/15 20:56
S7	33	silicon with powder same compress\$3 same thermal same melt\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/15 20:57
S8	1	silicon with powder same compress\$3 same thermal same melt\$3 and dop\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/15 20:58
S9	2	("7175685").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/15 21:01
S10	37	silicon with powder same (compress\$3 or compact\$3) same melt\$3 and dop\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/15 21:03
S11	2	("5431127").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/15 21:10
S12	9	"4040848"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/15 21:17
S13	1704	boron same melt\$3 same silicon same powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/15 21:23
S14	116	boron same melt\$3 same silicon powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/15 21:23
S15	22	boron with melt\$3 with silicon powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/15 21:23
S16	4	"5637524"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/08/15 23:04
S17	16	"4040849"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/12/26 22:39
S18	9	"4040848"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/12/26 22:42
S19	5918	silicon with germanium and powder and melt\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT;	ADJ	ON	2009/12/26 22:55

			IBM TDB			
S20	699	silicon with germanium same powder and melt\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2009/12/26 22:55
S21	173	silicon with germanium same powder and melt\$3 and compres\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2009/12/26 22:55
S22	59	silicon with germanium with powder and melt\$3 and compres\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2009/12/26 22:55
S23	0	("20010178675").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	OFF	2009/12/26 23:03
S24	2	("0537289").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	OFF	2010/01/03 22:41
S25	2	("5378289").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	OFF	2010/01/03 22:41
S26	14	straboni-alain.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2010/01/04 11:34
S27	2	("7465871").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	OFF	2010/01/04 11:35
S28	702	(136/236.1).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	OFF	2010/01/04 11:36
S29	1081	(438/510).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	OFF	2010/01/04 11:37
S30	2	("7563404").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	OFF	2010/06/23 09:33
S31	355	(264/614).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	OFF	2010/07/05 20:59
S32	2	("5431127").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	OFF	2010/07/05 21:00
S33	40	"5431127"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2010/07/05 21:00
S34	1122	(438/510).CCLS.	US-PGPUB; USPAT;	OR	OFF	2010/07/05

			USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB			21:04
S35	14	straboni-alain.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/20 17:10
S36	1137	(438/510).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/09/20 17:10
S37	34	silicon with powder same compress\$3 same thermal same melt\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/20 17:11
S38	3	santana and polysilicon and silicon with powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/20 17:11
S39	24	boron with melt\$3 with silicon powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/20 17:11
S40	62	silicon with germanium with powder and melt\$3 and compres\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/20 17:11
S41	359	(264/614).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/09/20 17:11
S42	40	polysilicon with wafer and silicon with powder and dop\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/20 17:12
S43	40	polysilicon with wafer and silicon with powder and dop\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/20 17:12
S44	9	"6494959"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/22 10:45
S45	1153	(438/510).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/12/19 19:38
S46	361	(264/614).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/12/19 19:38
S47	6	("3151379").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/12/19 19:39
S48	15	straboni-alain.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/12/19 19:39

S49	64	silicon with germanium with powder and melt\$3 and compres\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2010/12/19 19:39
S50	24	boron with melt\$3 with silicon powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2010/12/19 19:39
S51	34	silicon with powder same compress\$3 same thermal same melt\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2010/12/19 19:41
S52	3	santana and polysilicon and silicon with powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2010/12/19 19:41
S53	1170	(438/510).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	OFF	2011/06/01 12:33
S54	363	(264/614).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	OR	OFF	2011/06/01 12:33
S55	18	straboni-alain.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2011/06/01 12:33
S56	34	silicon with powder same compress\$3 same thermal same melt\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2011/06/01 12:33
S57	27	boron with melt\$3 with silicon powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2011/06/01 12:34
S58	44	polysilicon with wafer and silicon with powder and dop\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2011/06/01 12:34
S59	111	polysilicon with wafer and silicon with powder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2011/06/01 12:35
S60	67	silicon with germanium with powder and melt\$3 and compres\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2011/06/01 12:35

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